

Device Modeling Report

COMPONENTS: Power MOSFET (Model Parameters)
PART NUMBER: SSM3K7002FU
MANUFACTURER: TOSHIBA
Body Diode (Model Parameters) / ESD Protection



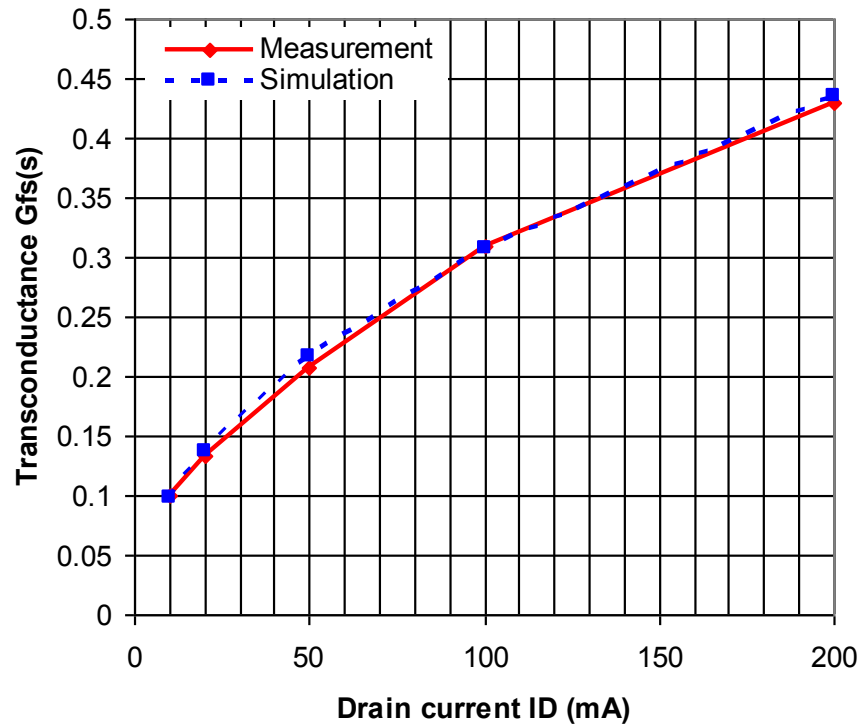
Bee Technologies Inc.

MOSFET MODEL PARAMETERS

PSpice model parameter	Model description
LEVEL	
L	Channel Length
W	Channel Width
KP	Transconductance
RS	Source Ohmic Resistance
RD	Ohmic Drain Resistance
VTO	Zero-bias Threshold Voltage
RDS	Drain-Source Shunt Resistance
TOX	Gate Oxide Thickness
CGSO	Zero-bias Gate-Source Capacitance
CGDO	Zero-bias Gate-Drain Capacitance
CBD	Zero-bias Bulk-Drain Junction Capacitance
MJ	Bulk Junction Grading Coefficient
PB	Bulk Junction Potential
FC	Bulk Junction Forward-bias Capacitance Coefficient
RG	Gate Ohmic Resistance
IS	Bulk Junction Saturation Current
N	Bulk Junction Emission Coefficient
RB	Bulk Series Resistance
PHI	Surface Inversion Potential
GAMMA	Body-effect Parameter
DELTA	Width effect on Threshold Voltage
ETA	Static Feedback on Threshold Voltage
THETA	Mobility Modulation
KAPPA	Saturation Field Factor
VMAX	Maximum Drift Velocity of Carriers
XJ	Metallurgical Junction Depth
UO	Surface Mobility

Transconductance Characteristic

Circuit Simulation Result

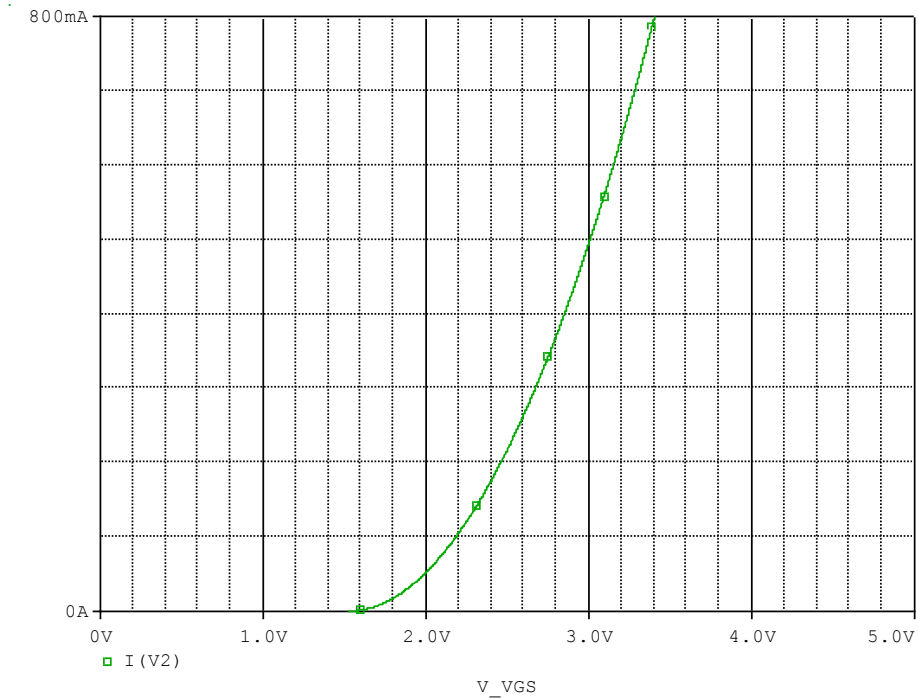


Comparison table

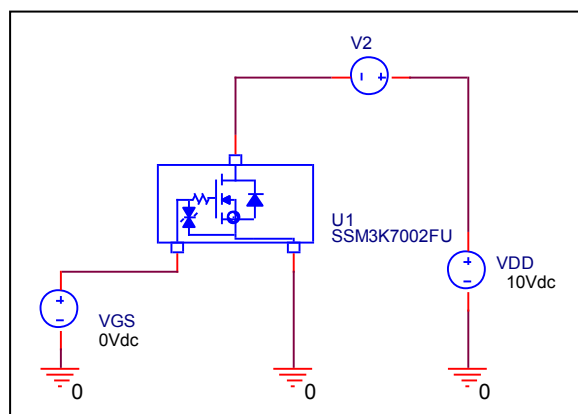
Id(mA)	Gfs(S)		Error(%)
	Measurement	Simulation	
10	0.1	0.098039216	-1.96
20	0.133	0.137931034	3.71
50	0.208	0.217391304	4.52
100	0.31	0.307692308	-0.74
200	0.43	0.434782609	1.11

Vgs-Id Characteristic

Circuit Simulation result

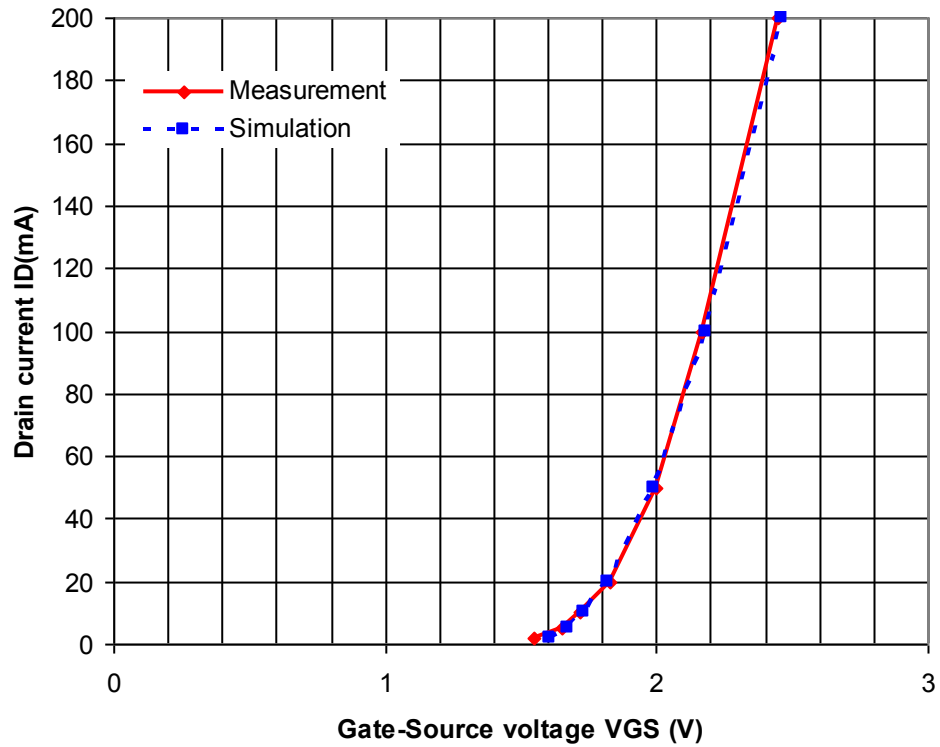


Evaluation circuit



Comparison Graph

Circuit Simulation Result

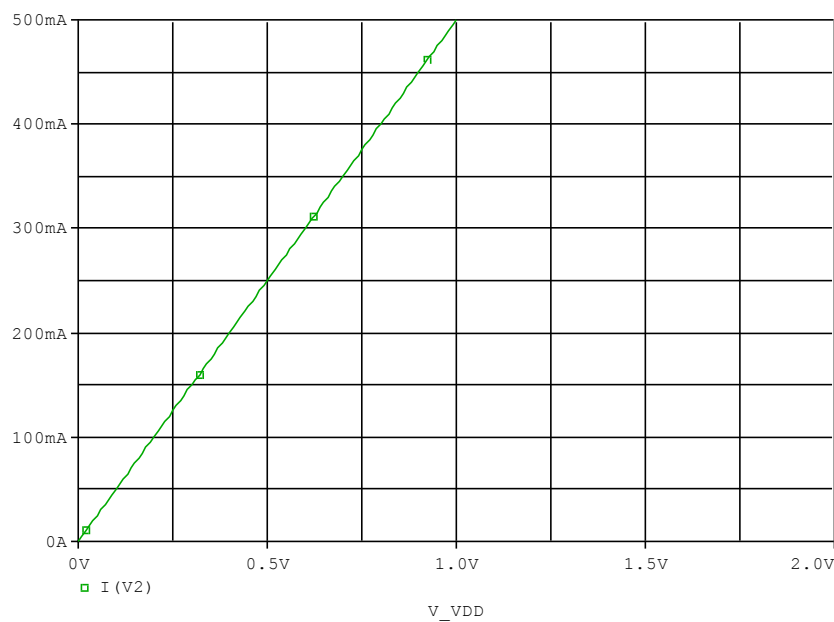


Simulation Result

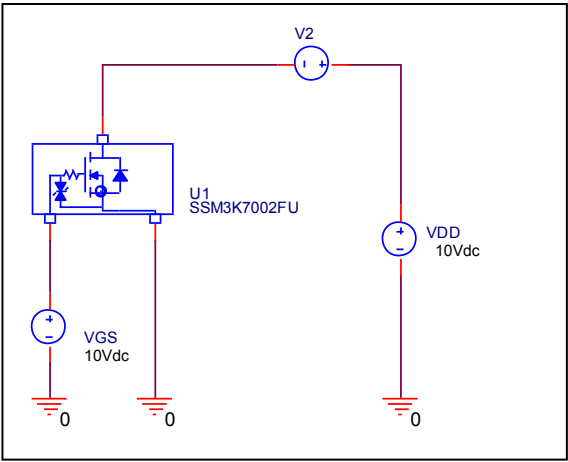
I_D (mA)	V_{GS} (V)		Error (%)
	Measurement	Simulation	
2	1.55	1.61	3.87
5	1.65	1.67	1.21
10	1.72	1.73	0.58
20	1.83	1.82	-0.55
50	2.00	1.99	-0.50
100	2.17	2.18	0.46
200	2.45	2.46	0.41

Rds(on) Characteristic

Circuit Simulation result



Evaluation circuit

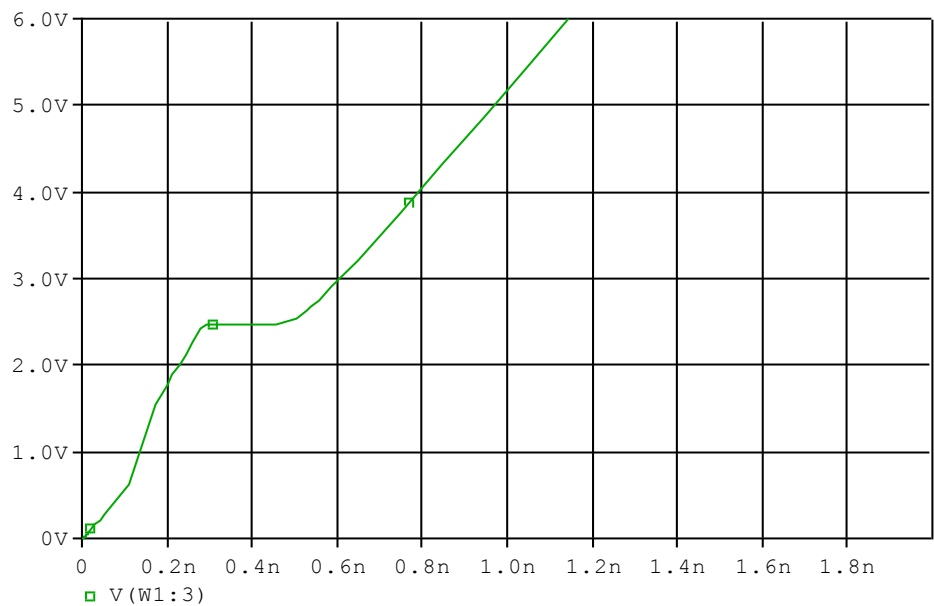


Simulation Result

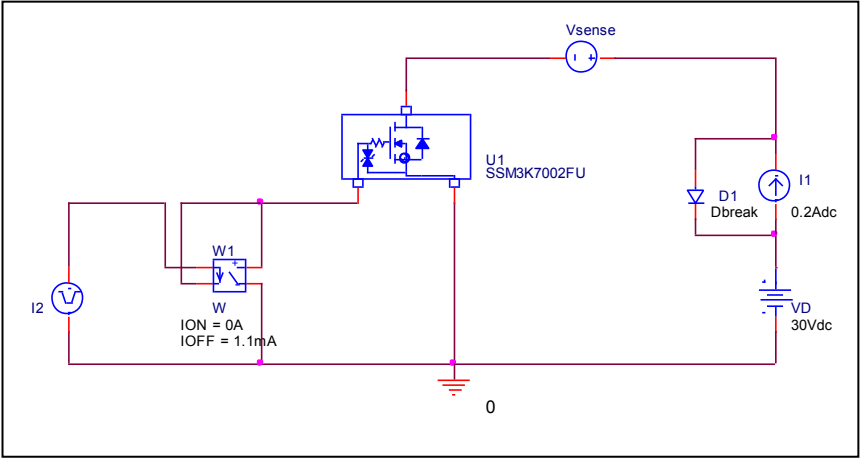
$I_D=500\text{mA}$, $V_{GS}=10\text{V}$	Measurement		Simulation		Error (%)
$R_{DS} \text{ (on)}$	2.0	Ω	2.0	Ω	0.0

Gate Charge Characteristic

Circuit Simulation result

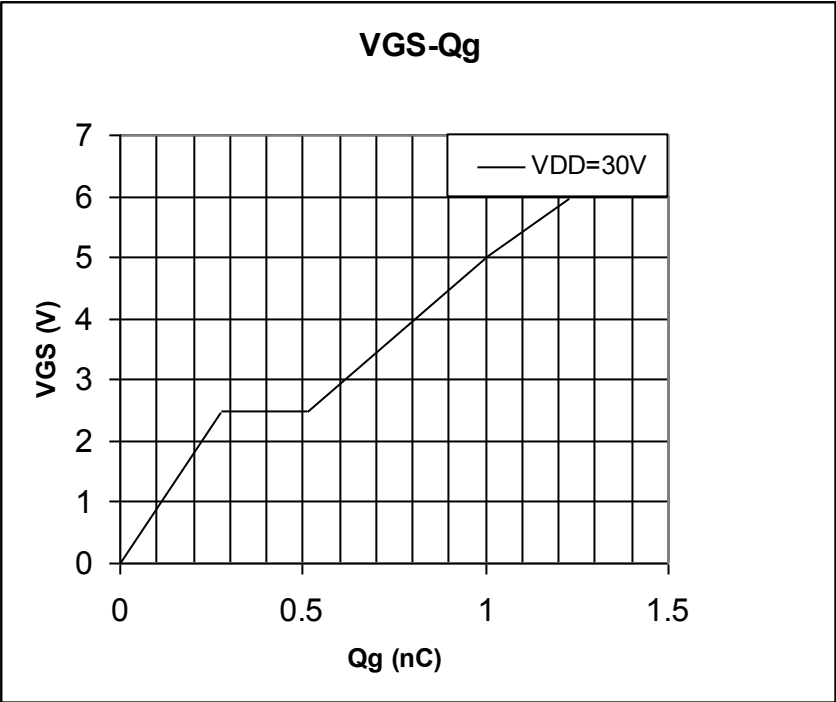


Evaluation circuit

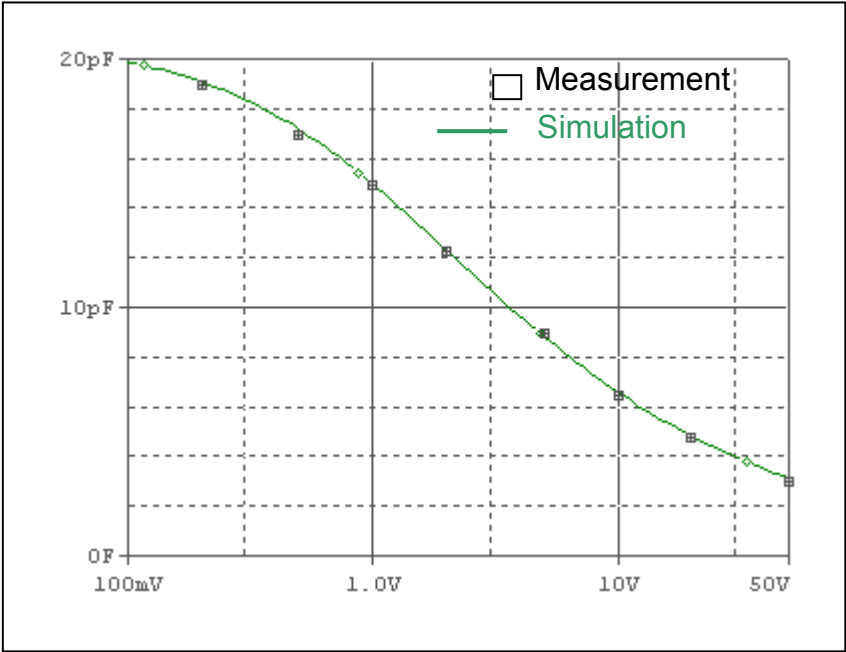


Simulation Result

$V_{DD}=30V$, $I_D=200mA$, $V_{GS}=5V$	Measurement		Simulation		Error (%)
Qgs	0.280	nC	0.286	nC	2.14
Qgd	0.236	nC	0.230	nC	-2.54



Capacitance Characteristic

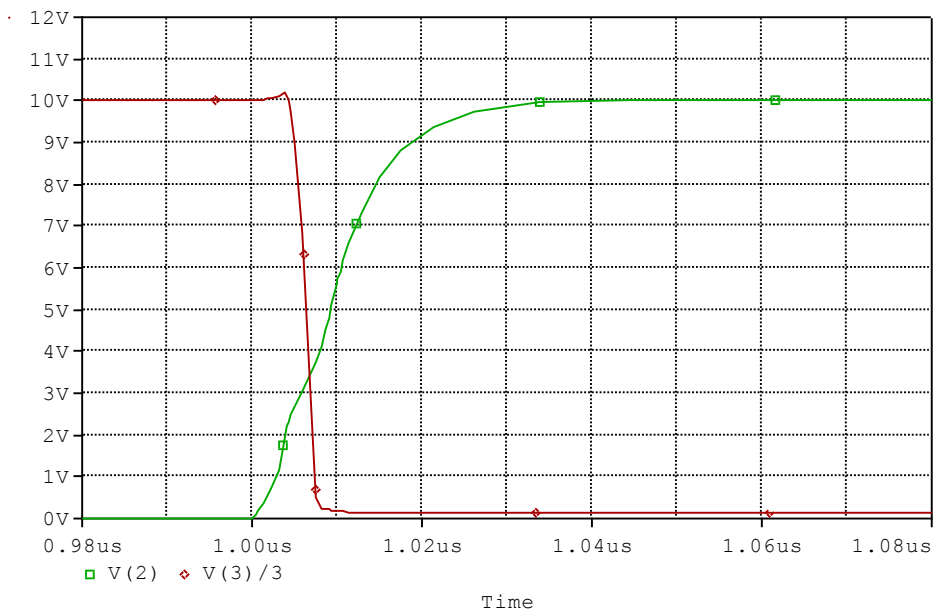


Simulation Result

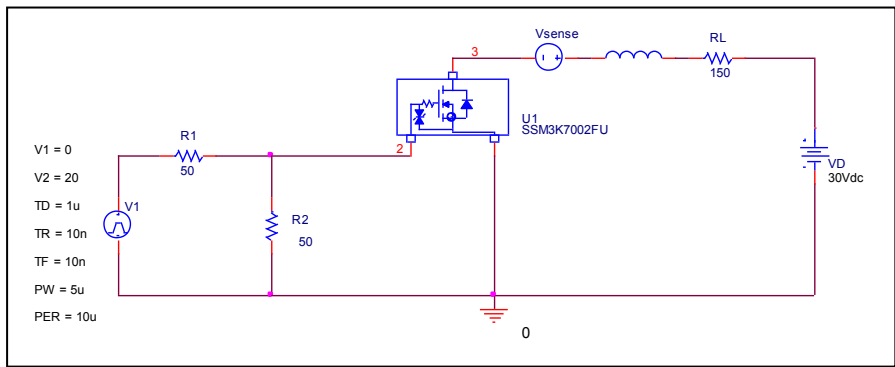
V _{DS} (V)	Cbd(pF)		Error(%)
	Measurement	Simulation	
0.1	20	19.87	-0.65
0.2	19	19.07	0.37
0.5	17	17.15	0.88
1	15	14.946	-0.36
2	12.3	12.315	0.12
5	8.8	8.82	0.23
10	6.5	6.58	1.23
20	4.8	4.815	0.31
50	3.1	3.15	1.61

Switching Time Characteristic

Circuit Simulation result



Evaluation circuit

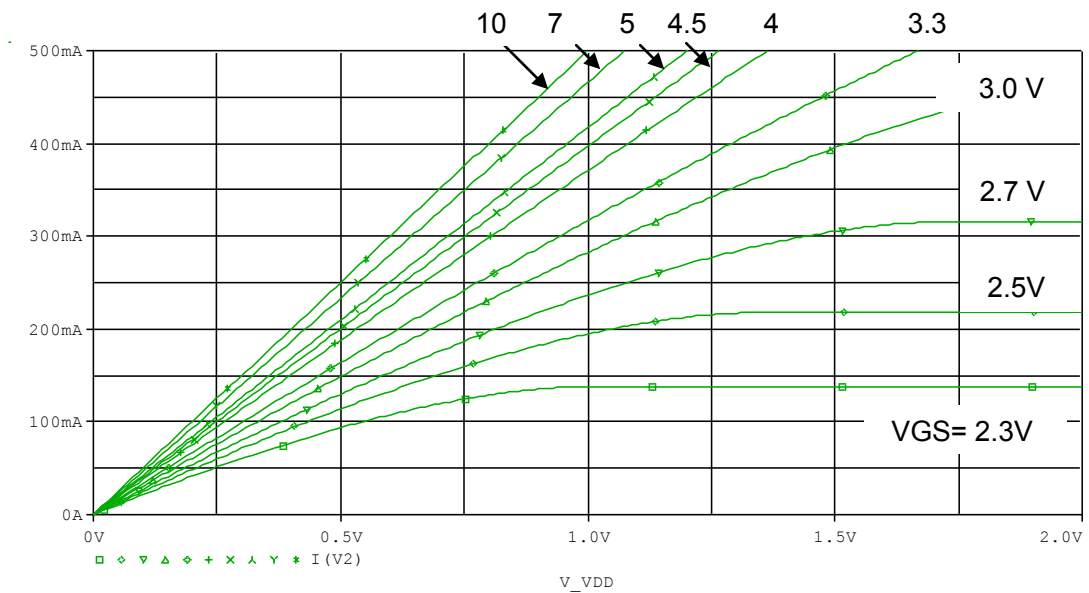


Simulation Result

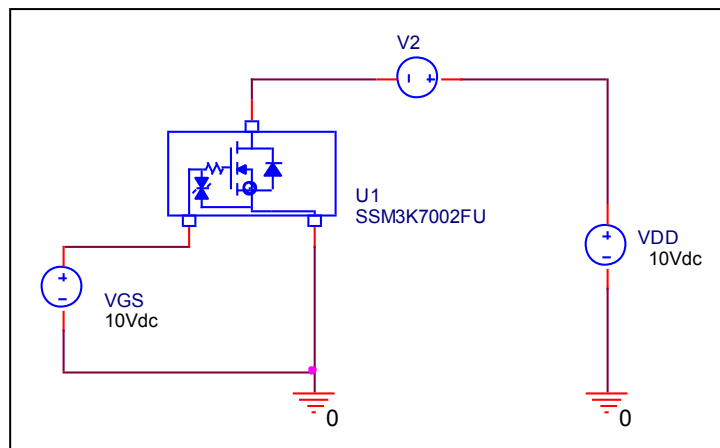
$I_D=0.2A$, $V_{DD}=30V$, $V_{GS}=0/10V$	Measurement		Simulation		Error(%)
	Td(on)	2.400 ns	2.418 ns	ns	
					0.75

Output Characteristic

Circuit Simulation result



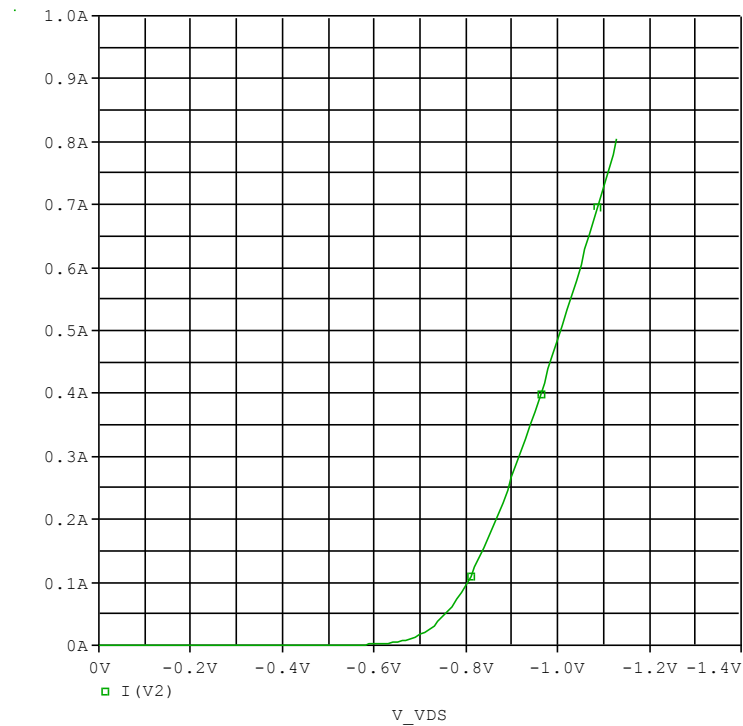
Evaluation circuit



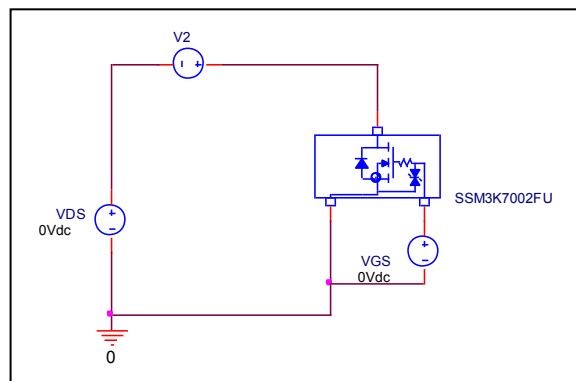
BODY DIODE SPICE MODEL

Forward Current Characteristic

Circuit Simulation Result

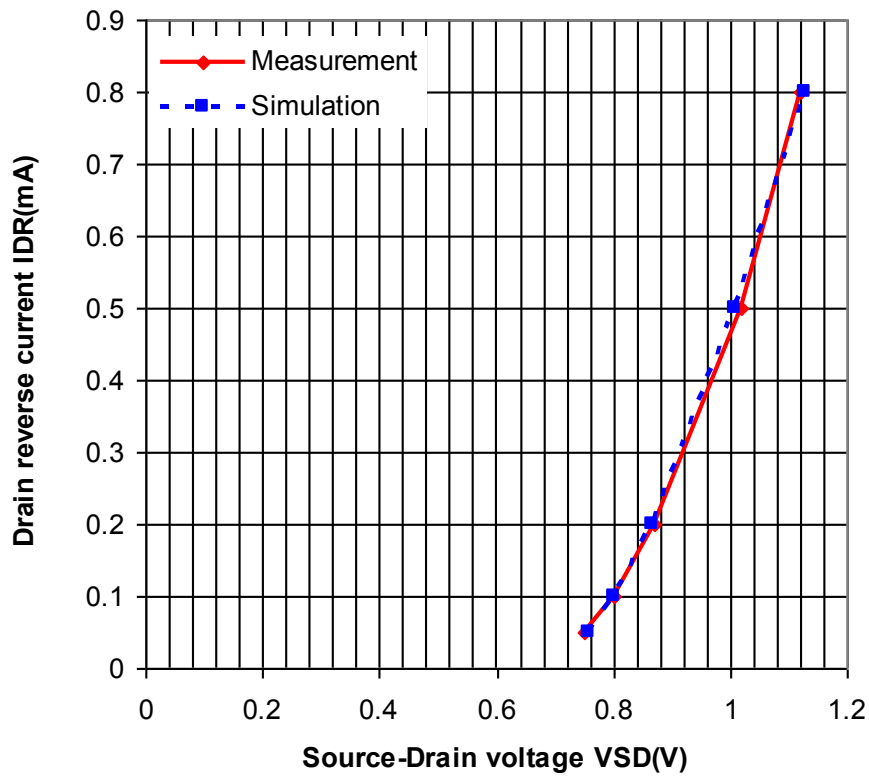


Evaluation Circuit



Comparison Graph

Circuit Simulation Result

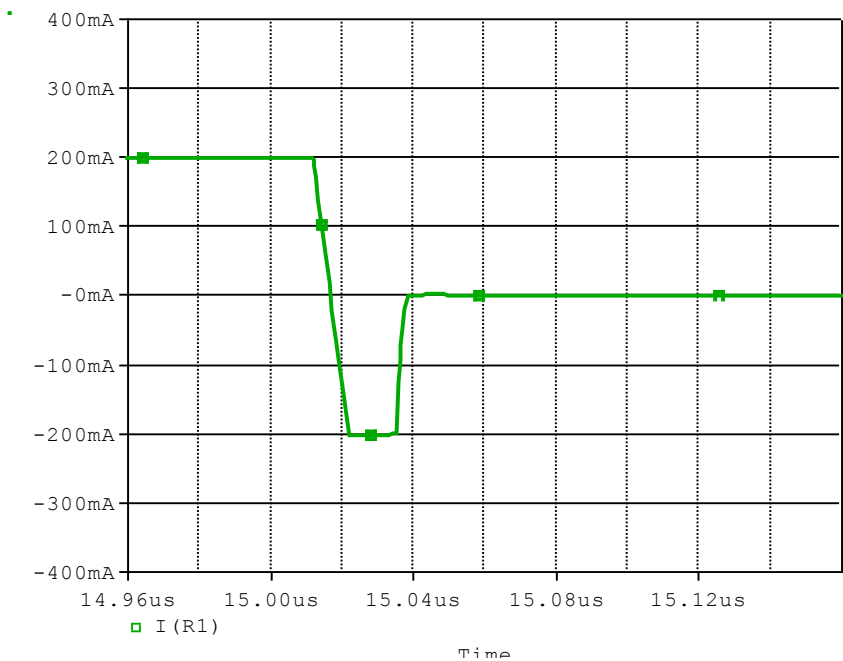


Simulation Result

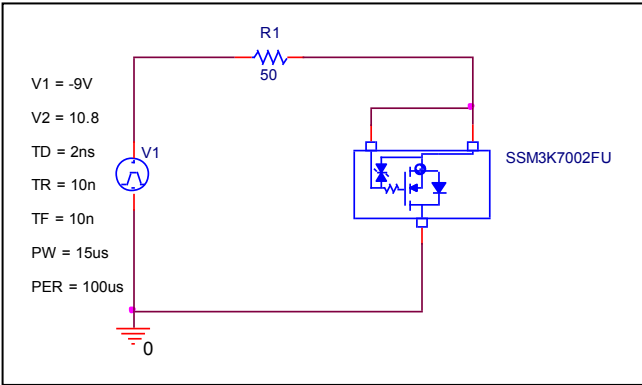
IDR(A)	VSD(V)		%Error
	Measurement	Simulation	
0.05	0.75	0.757	0.93
0.1	0.8	0.803	0.38
0.2	0.87	0.866	-0.46
0.5	1.02	1.007	-1.27
0.8	1.12	1.129	0.80

Reverse Recovery Characteristic

Circuit Simulation Result



Evaluation Circuit

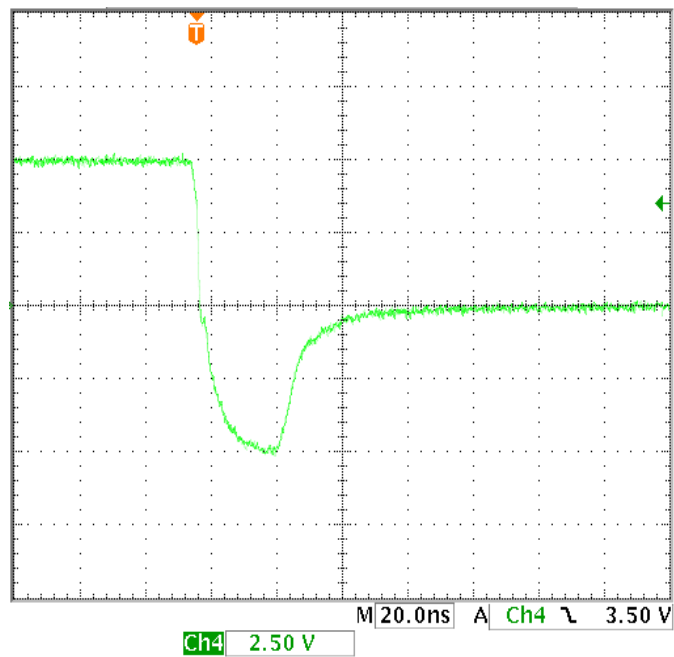


Compare Measurement vs. Simulation

	Measurement		Simulation		Error (%)
trj	17.000	ns	16.947	ns	-0.31176
trb	24.000	ns	3.9564	ns	-83.515
trr	41.000	ns	20.9034	ns	-49.0161

Reverse Recovery Characteristic

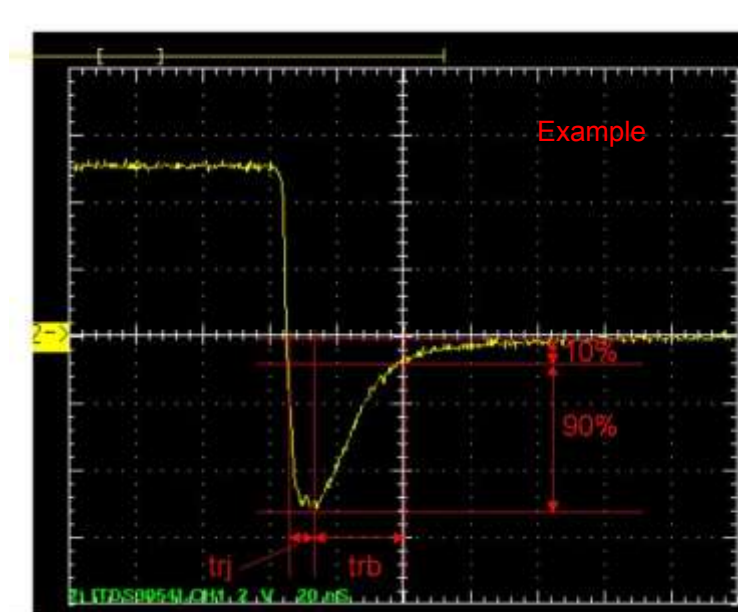
Reference



$T_{rr} = 17 \text{ (ns)}$

$T_{rb} = 24 \text{ (ns)}$

Conditions: $I_{fwd} = I_{rev} = 0.2 \text{ (A)}$, $R_L = 50$

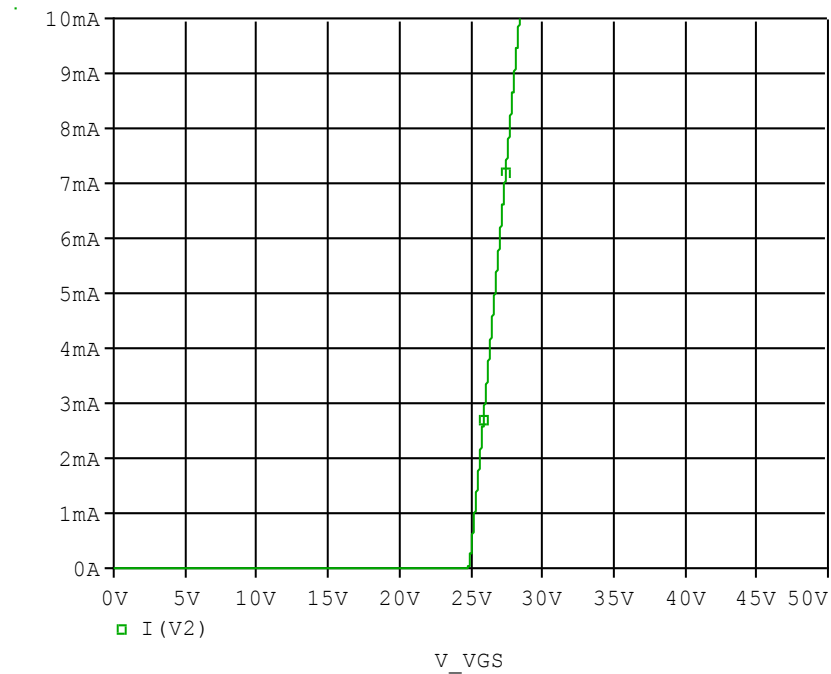


Relation between t_{rr} and τ_{rb}

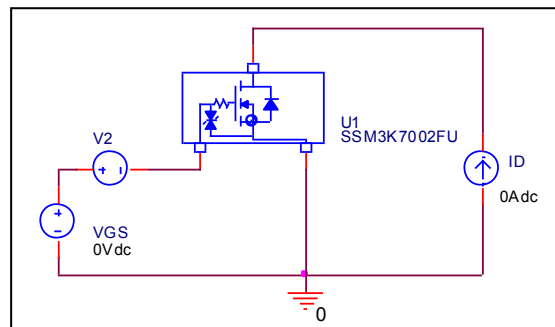
ESD PROTECTION DIODE SPICE MODEL

Zener Voltage Characteristic

Circuit Simulation Result



Evaluation Circuit



Zener Voltage Characteristic

Reference

